

# Evaluating Solar Panel Mechanical Durability of Commercial Modules

Eric Schneller<sup>1</sup>

Jason Lincoln<sup>1</sup>, Hubert Seigneur<sup>1</sup>, Joseph Walters<sup>1</sup>, Andrew M. Gabor<sup>2</sup>

<sup>1</sup> Florida Solar Energy Center, University of Central Florida

<sup>2</sup> Brightspot Automation

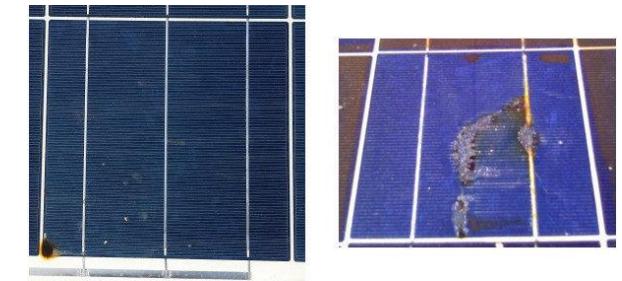


# Outline

- **Motivation:** Impact of Cell Cracks and their Origin
- **Methodology:** Typical Mechanical Evaluation Approaches
- **Experimental Results:** Case Study of Commercial Modules
- **Discussion / Conclusions**

# Module Mechanical Durability

- PV modules experience a wide range of mechanical stressors over their lifetime that may cause cell cracking
  - shipping, installation, snow, wind, thermal cycling
- Cell cracks pose a risk to long term performance
  - Increase in **series resistance**
  - Increase in “dead area” leading to **current mismatch**
  - Potential for **hot spot** generation
  - Severe hot spots are a potential **safety hazard**
- In this work, a modified mechanical durability test sequence is investigated to evaluate module design with respect to crack durability

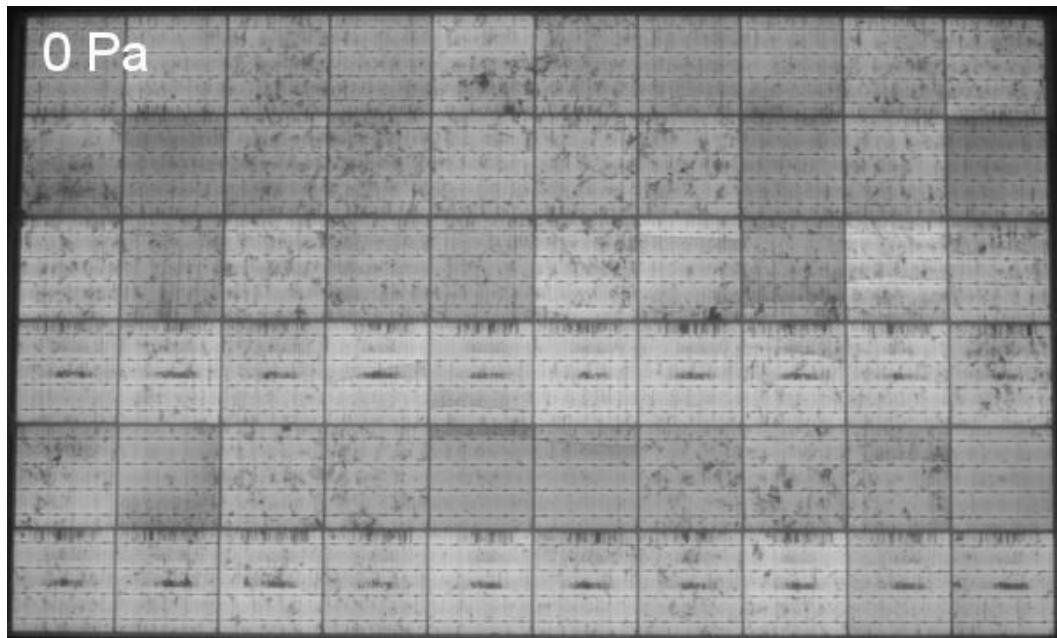


Example severe hot spot caused due to cell cracks [1]

# METHODOLOGY

# Mechanical Testing Equipment - LoadSpot

- Front side is unobstructed to allow for *in-situ* characterization under load
- Electroluminescence Camera and Sinton FMT solar simulator are used for characterization



 **BrightSpot Automation**

 **Sinton**  
instruments

# Typical Mechanical Evaluations – Front Side Loads

- A front side mechanical load puts cells into tension, which propagates micro-cracks into full cell cracks.
- These cell cracks tend to close upon removal of the mechanical load
- This results in very minimal power degradation even with a large number of fractured cells

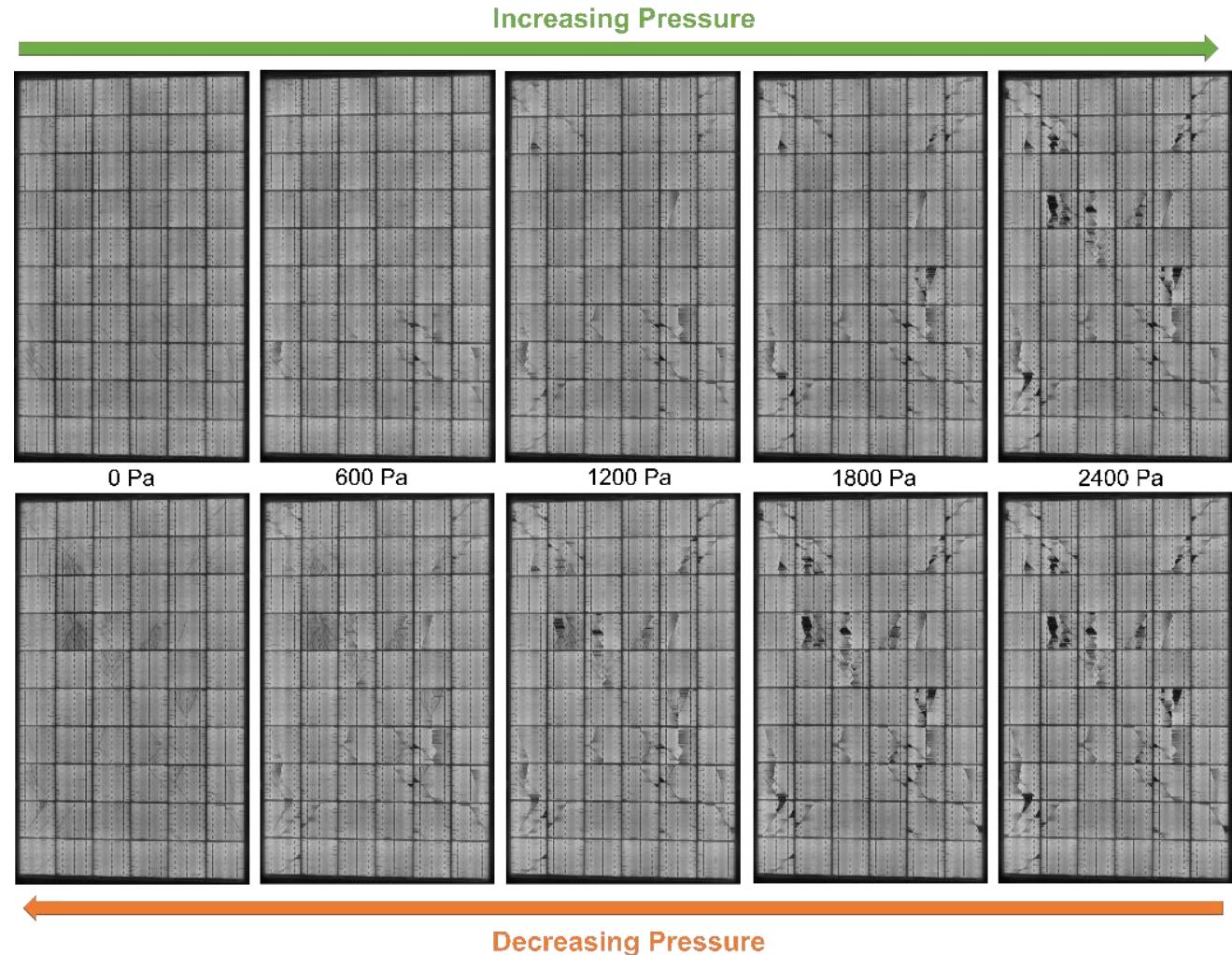
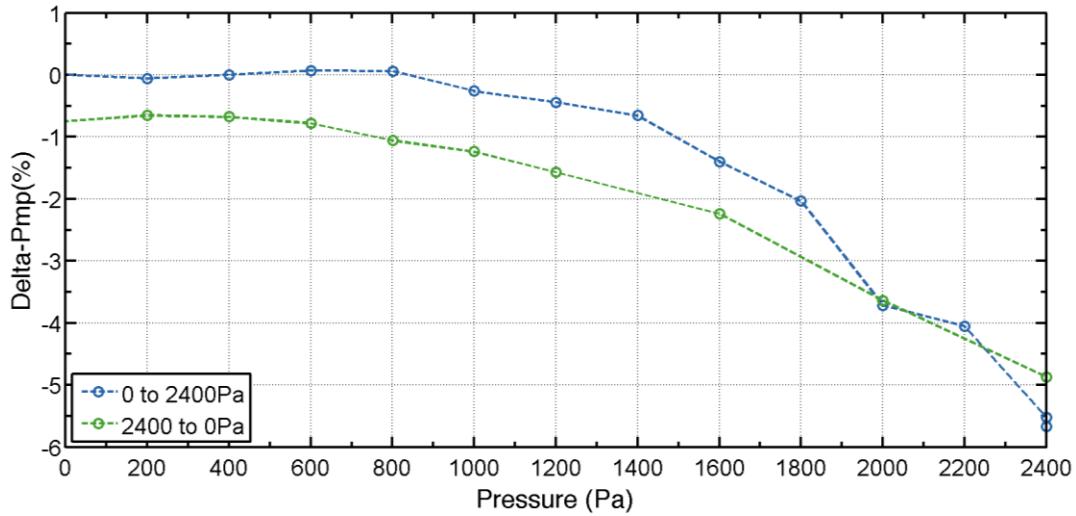
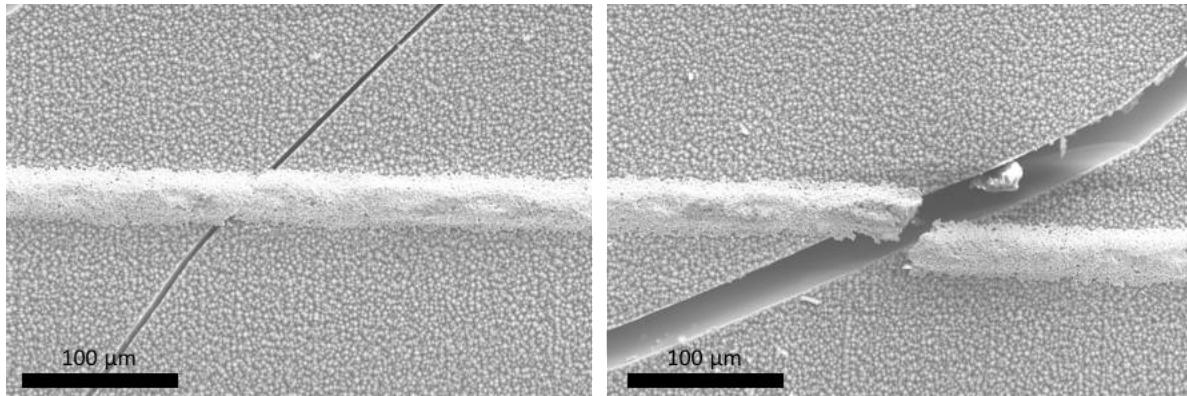


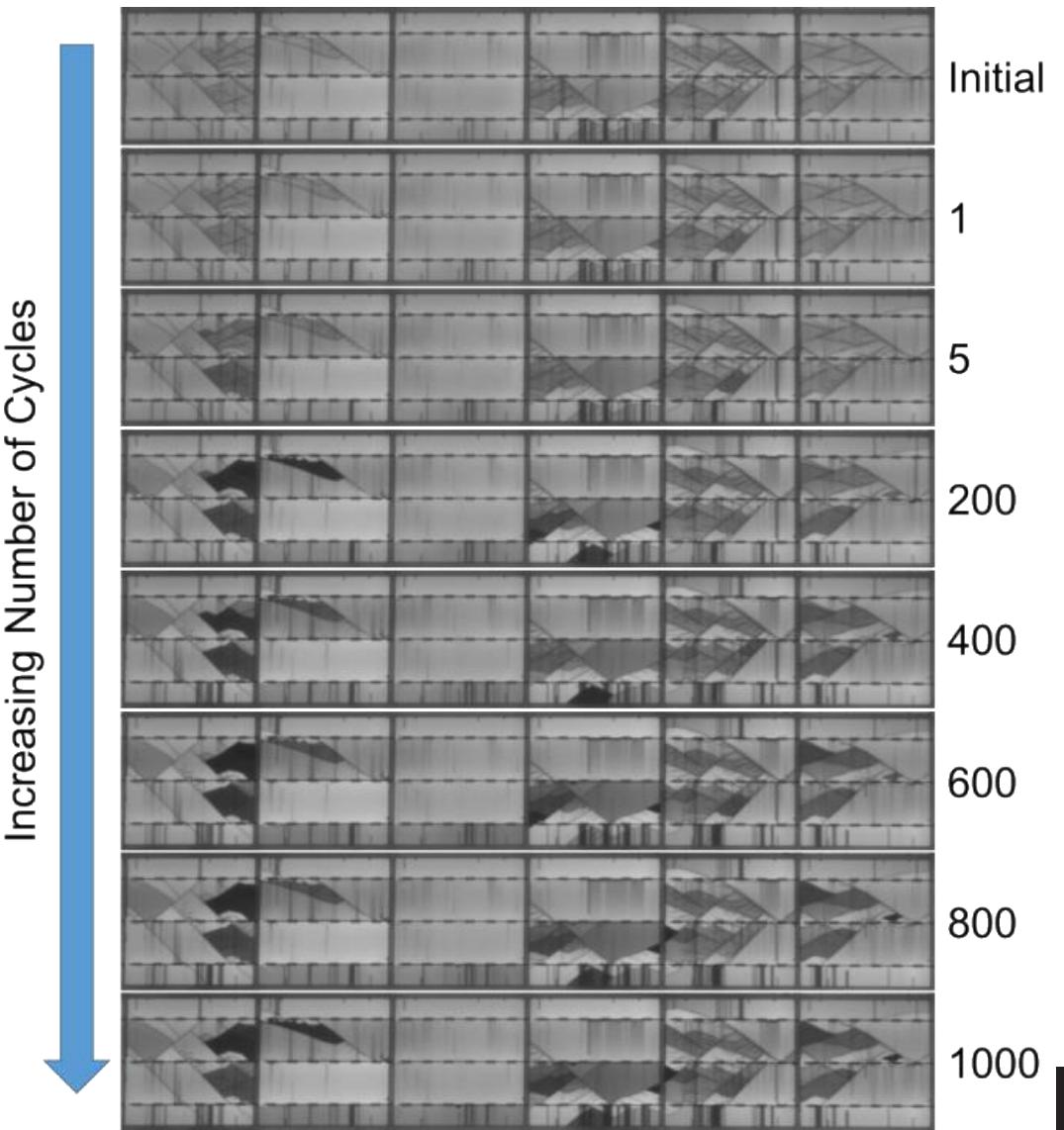
Figure: Change in maximum power as a function of applied load for both increasing (blue) and decreasing (green) pressure

# Typical Mechanical Evaluations – Cyclic Loading

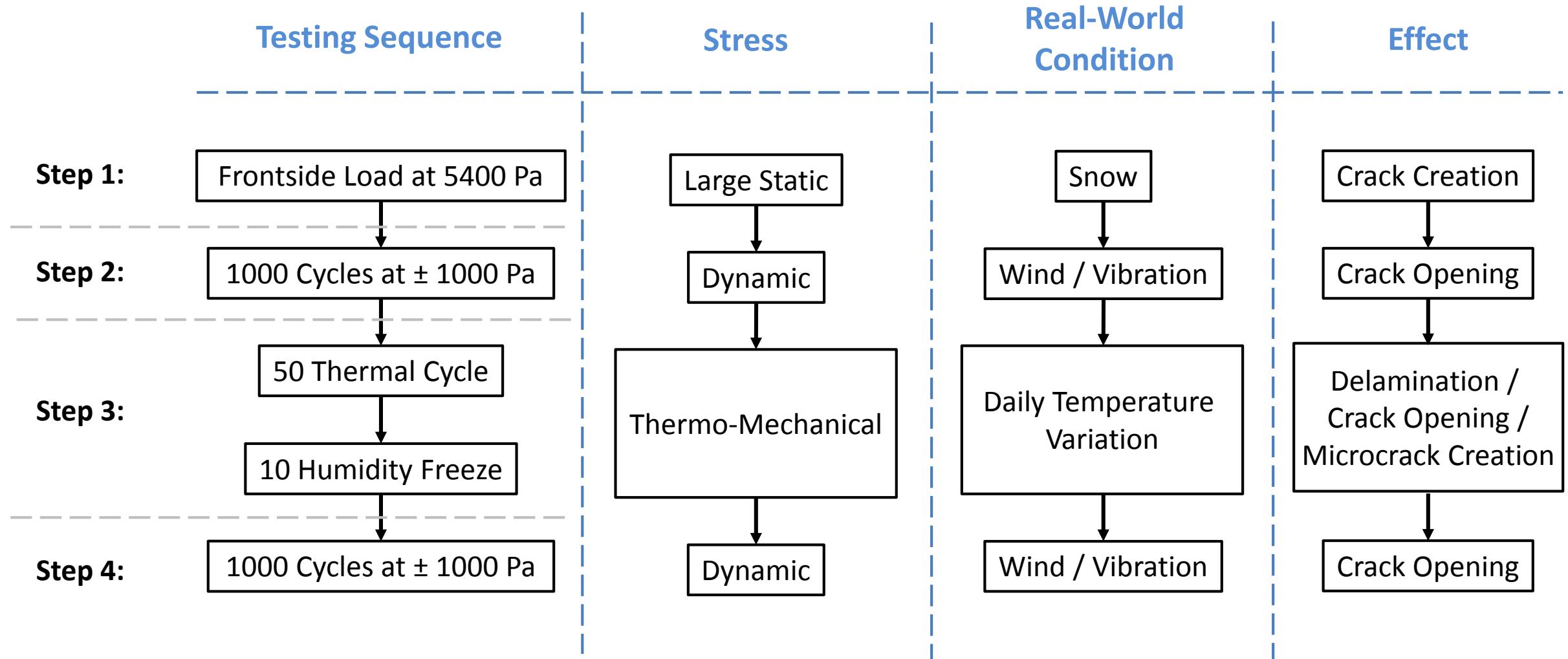
- Standard Cyclic loading sequence is 1000 cycles of  $\pm 1000\text{Pa}$
- Cyclic loading assists in the transition of benign cracks into electrical isolation
- Electrical isolation has been directly related to power loss



SEM images of cell cracks that exhibit electrical conduction (left) and electrical isolation (right) of the metallization



# Mechanical Evaluation Protocol



**Objective:** Evaluate a module design with respect to crack creation and crack opening

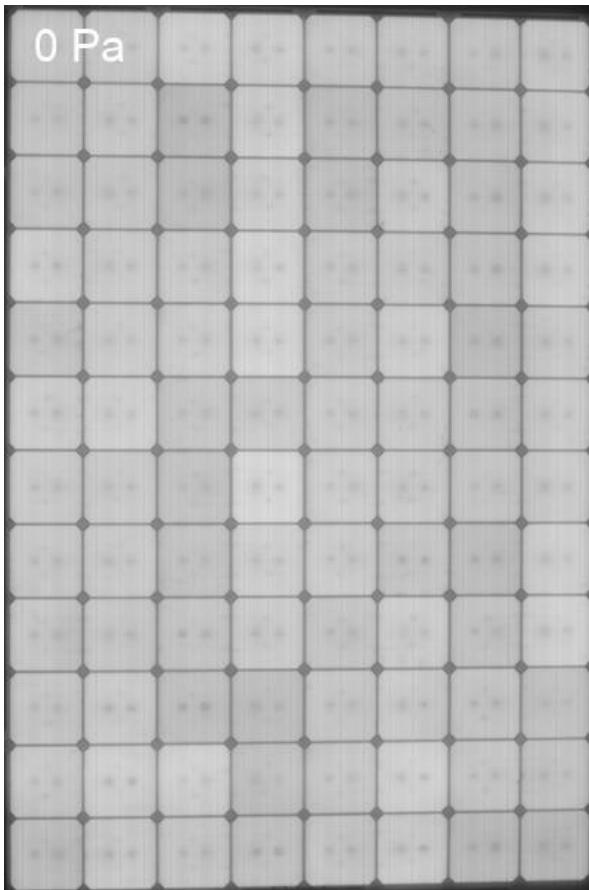
# EXPERIMENTAL RESULTS

# Module Technologies

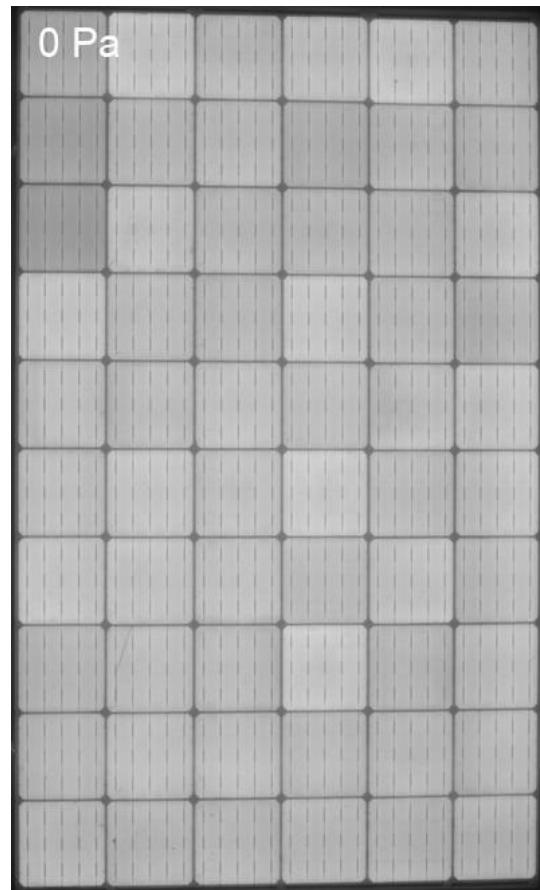
Cell Technology	Interconnect Technology	Cell Size	Number of Cells
HIT	3 Busbar Low Temperature Interconnects	5 inch pseudo-square	96
Mono-PERC	4 Busbar Solder Interconnects	6 inch pseudo-square	60
Multi-PERC	4 Busbar Solder Interconnects	6 inch square	60
Mono-PERT	Wire Interconnects	6 inch pseudo-square	60

# Step 1 – Static Load – Crack Creation

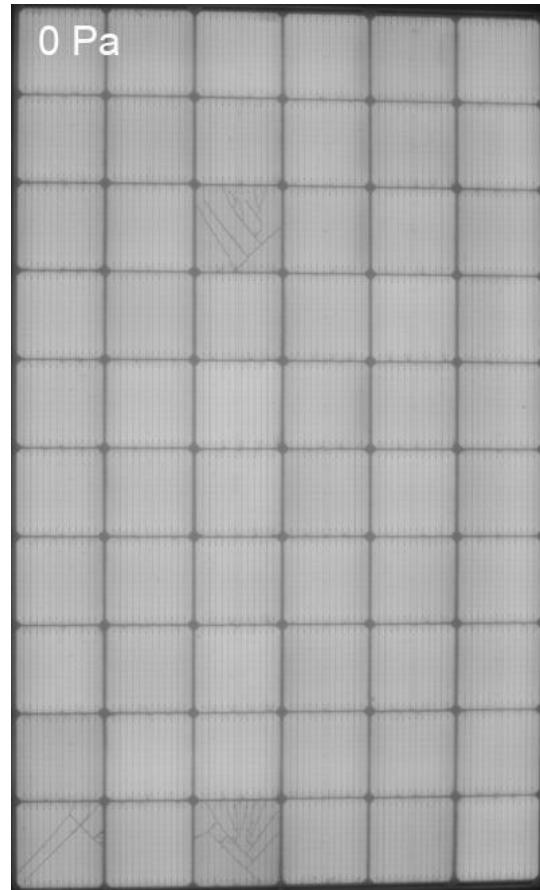
Frontside Load up to 5400Pa



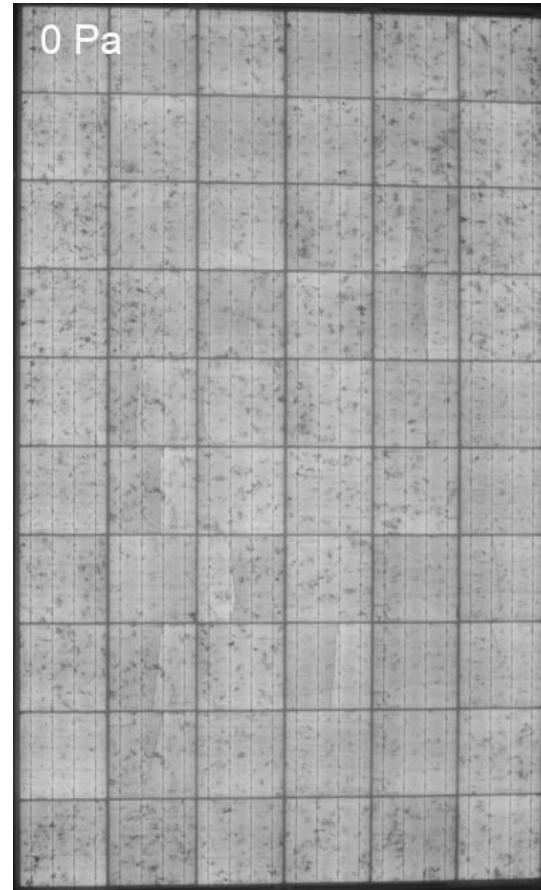
HIT  
**0 Cracked Cell**



Mono-PERC  
**4 Cracked Cells**



Mono-PERT  
**7 Cracked Cells**



Multi-PERC  
**37 Cracked Cells**

- There is a clear differentiation between module designs with respect to crack creation with a front-side load up to 5400 Pa

## Step 2 – Cyclic Loading – Crack Opening

1000 Cycles at  $\pm 1000\text{Pa}$

0 Cycles

0 Cycles

0 Cycles

0 Cycles

1000 Cycles

1000 Cycles

1000 Cycles

1000 Cycles

HIT

**No Change**

Mono-PERC  
**No Change**

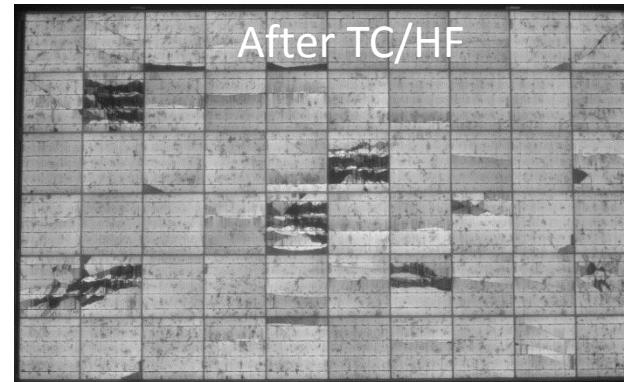
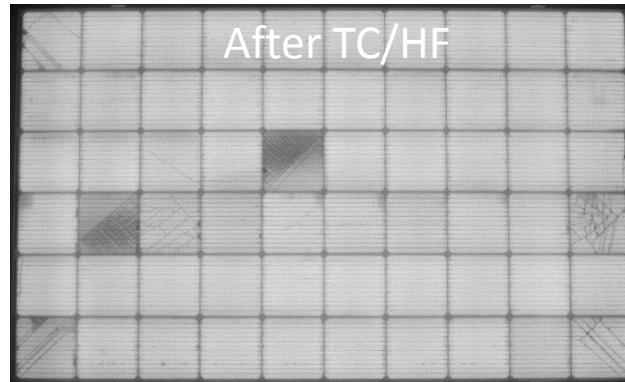
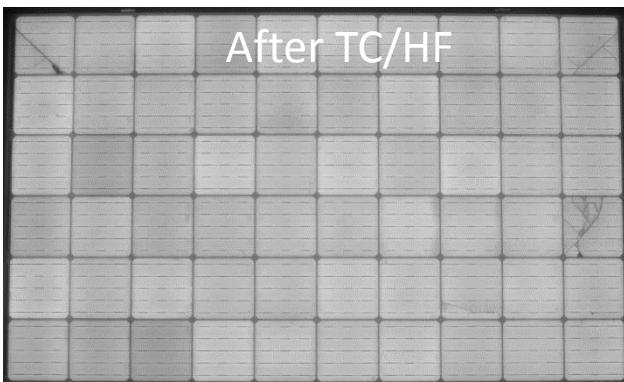
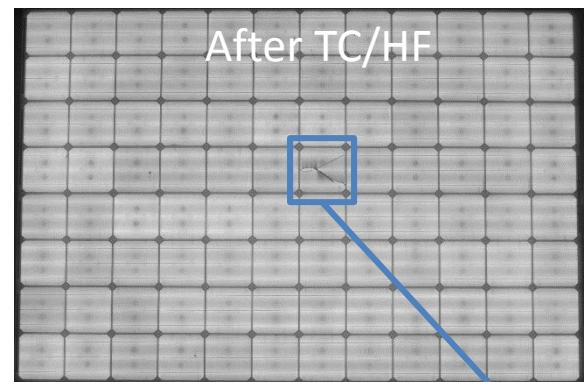
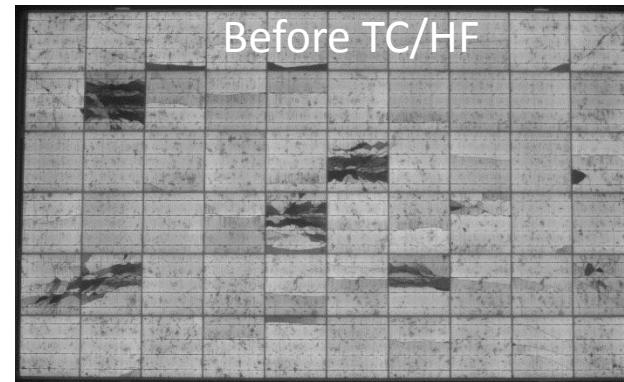
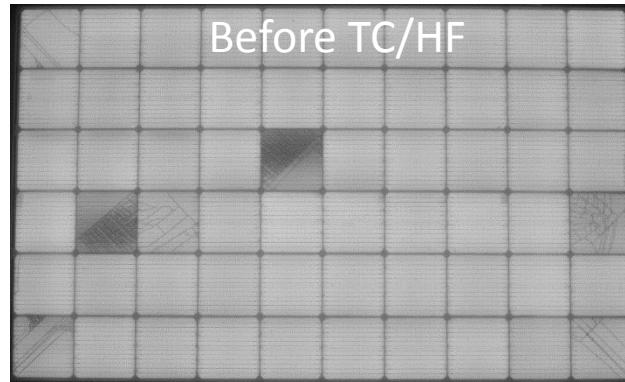
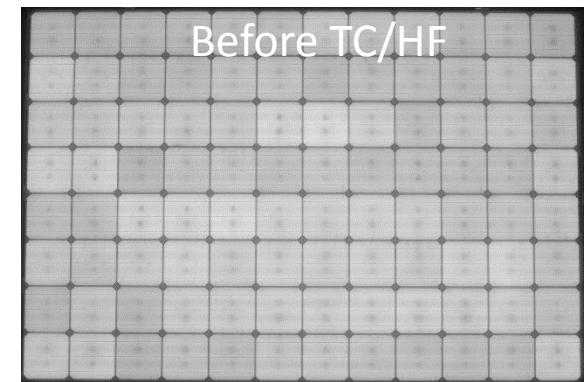
Mono-PERT  
**No Change**

Multi-PERC  
**Multiple Open Cracks Form**

- Cyclic loading tends to open cracks on heavily damaged modules (see Multi-PERC)
- Wire interconnects appear to prevent crack opening due to redundant design (see Mono-PERT)

# Step 3 – Environmental Chamber

TC50 / HF10



HIT

**No Change** **Handling Mistake** **No Significant Change**  
During Transportation

Mono-PERC

Mono-PERT

**Several New Cracks Form**

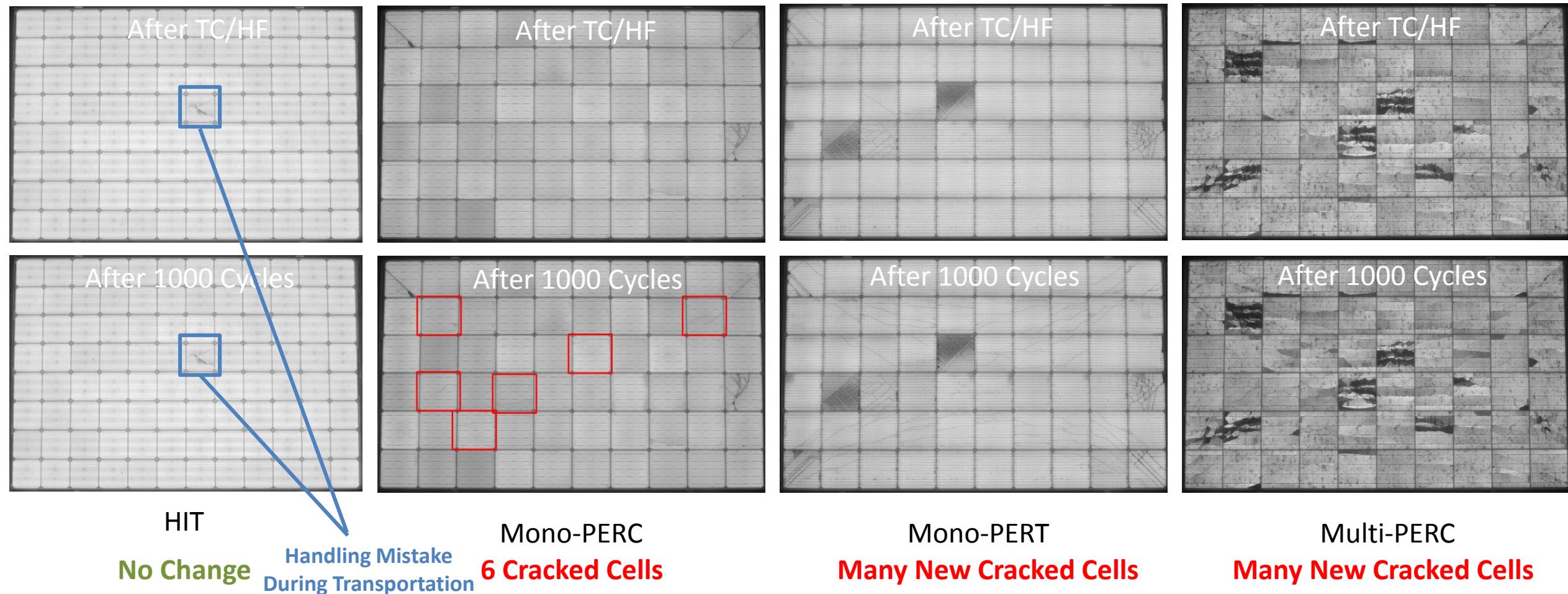
Multi-PERC

**Slight Increase in**  
**Crack Opening**

- Very minimal change in power for all modules
- Minor change in number of cracks and dark area associated with cracks for Mono-PERT and Multi-PERC

# Step 4 – Final Mechanical Stress

1000 Cycles at  $\pm 1000\text{Pa}$



- Thermal Cycling has a major impact on the creation of micro-cracks<sup>1,2</sup>
- Cell cracks appear to initiate near busbars and propagate with only a mild load of 1000 Pa for Mono-PERT and Multi-PERC Modules.
- The interconnect scheme and choice of encapsulant is the likely reason for superior performance of HIT Modules

[1] Seigneur, Hubert et al. "Micro-crack Formation in Silicon Solar Cells during Cold Temperatures" *In Press - IEEE JPV*

[2] Rowell, Michael et al. "The Effect of Laminate Construction and Temperature Cycling on the Fracture Strength and Performance of Encapsulated Solar Cells." *2018 IEEE WCPEC 3927-3931*.

# Power Degradation

*I-V* data was captured to assess the impact on performance due to each exposure step.

## High Power Loss (> 5%)

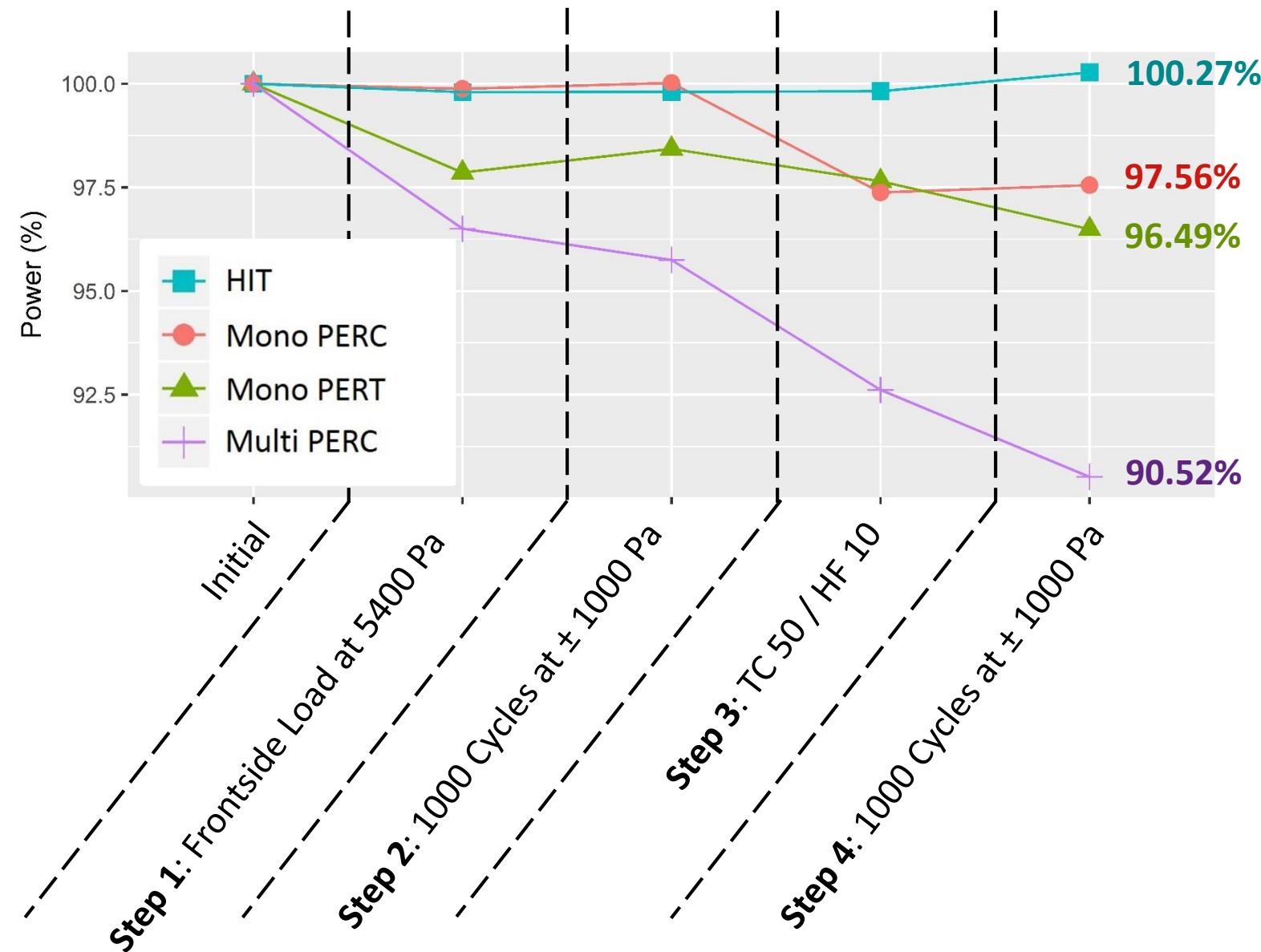
- Multi PERC

## Mild Power Loss (2-5%)

- Mono PERT
- Mono PERC

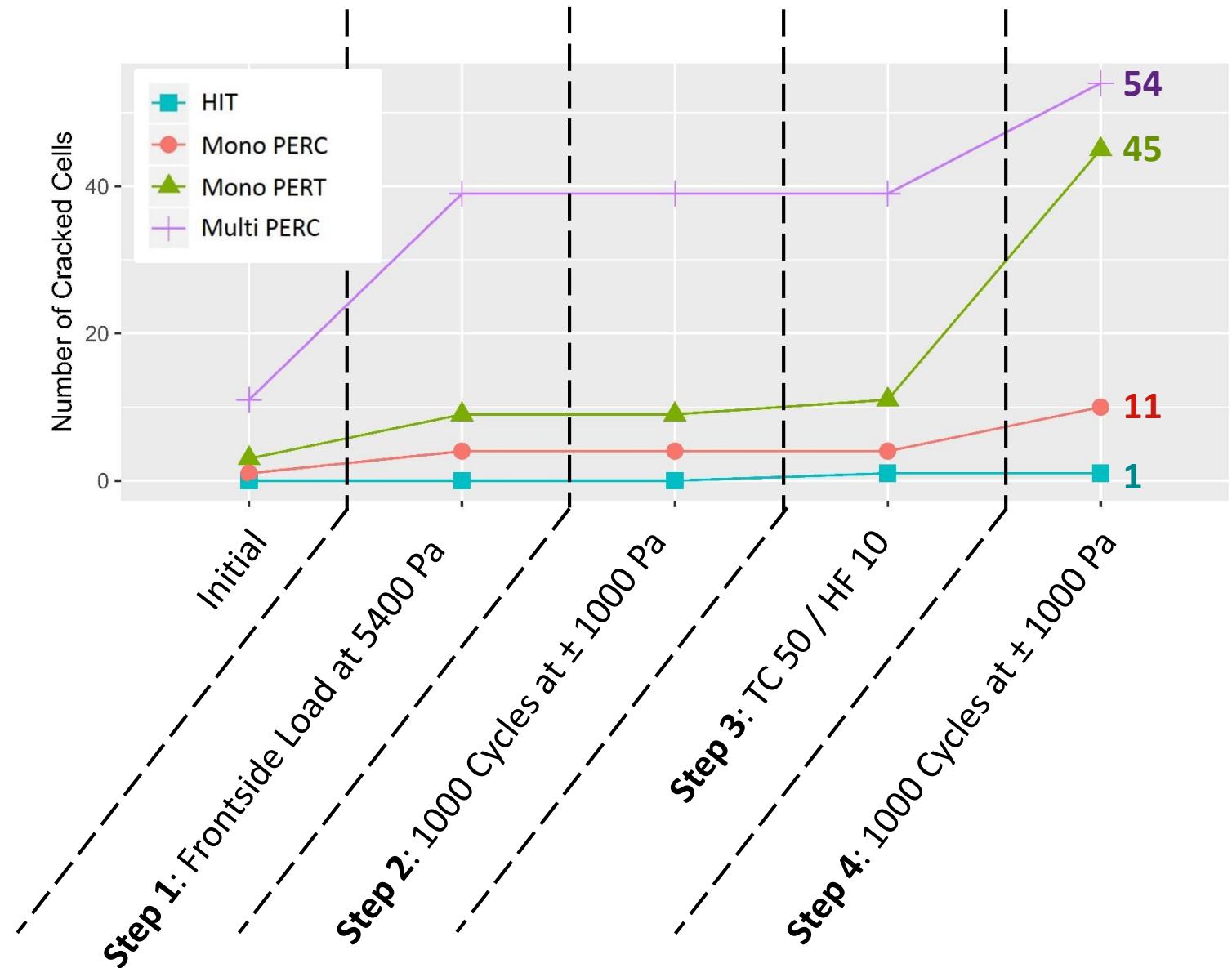
## No Significant Power Loss

- HIT



# Crack Creation

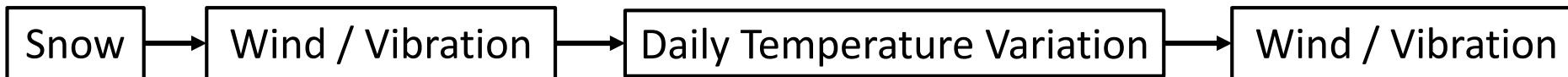
- The number of cracked cells were counted to identify which exposure steps contributed to cell cracks
- The initial frontside load of 5400Pa and the mechanical load after TC/HF contributed the most number of new cracked cells
- The HIT module only exhibited a single crack, which was the result of a handling mistake during transportation



# **DISCUSSION / CONCLUSION**

# Discussion

- A modified testing sequence was proposed to evaluate module design with respect to crack durability
  - A large front side static load is used to create cracks
  - Subsequent cyclic loading and thermal cycling is used to open cracks



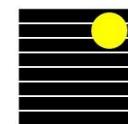
- Key Takeaways
  1. Large variation in crack durability across commercially available modules
  2. HIT modules, utilizing a symmetric cell structure and low temperature interconnect process, exhibit high durability with respect to crack generation
  3. Mechanical loading after thermal cycling causes a significant number of new cracks for modules with solder interconnects



**SOLAR ENERGY  
TECHNOLOGIES OFFICE**  
U.S. Department Of Energy

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**Panasonic**



**BrightSpot Automation**

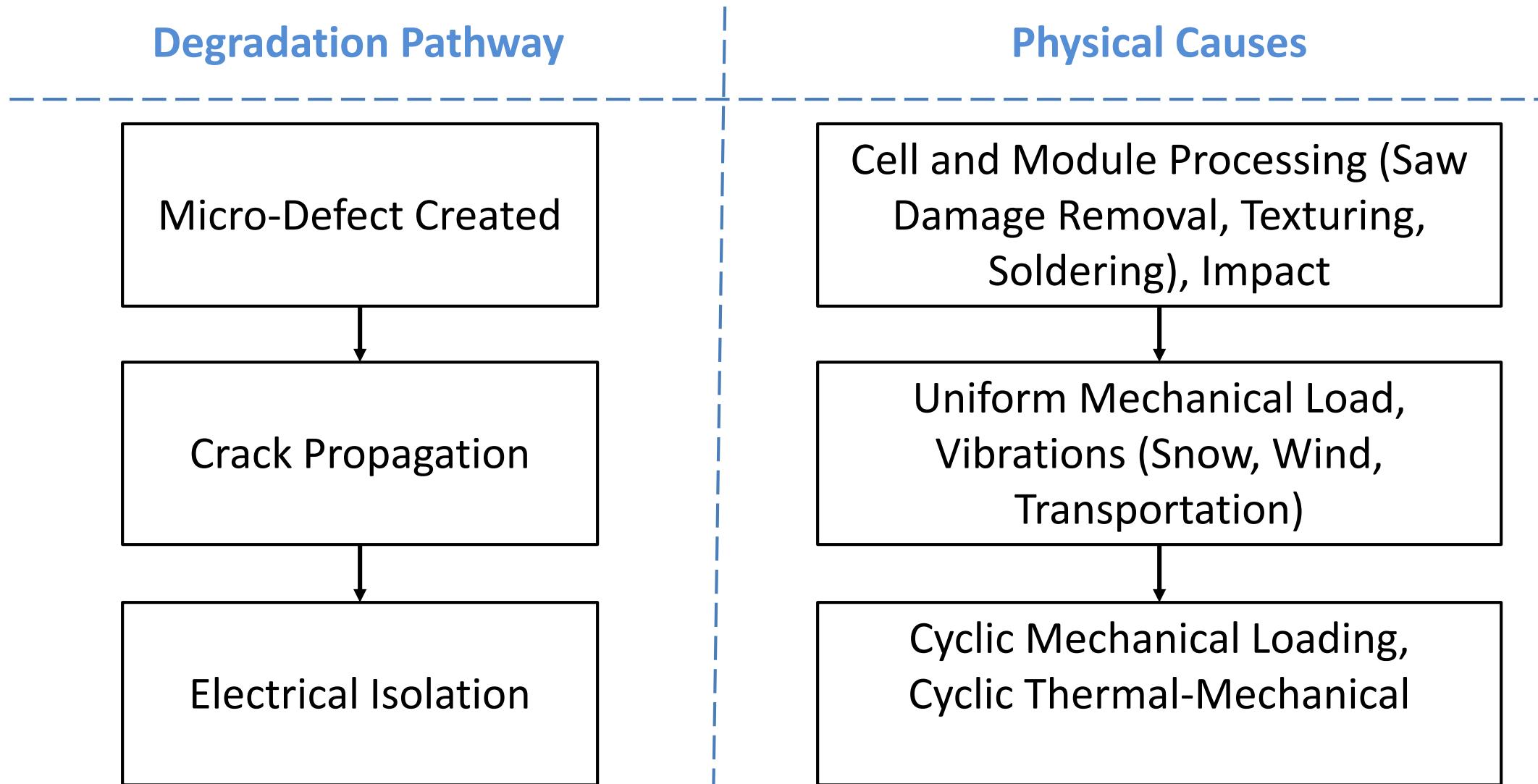
**THANK YOU**

[eschneller@fsec.ucf.edu](mailto:eschneller@fsec.ucf.edu)

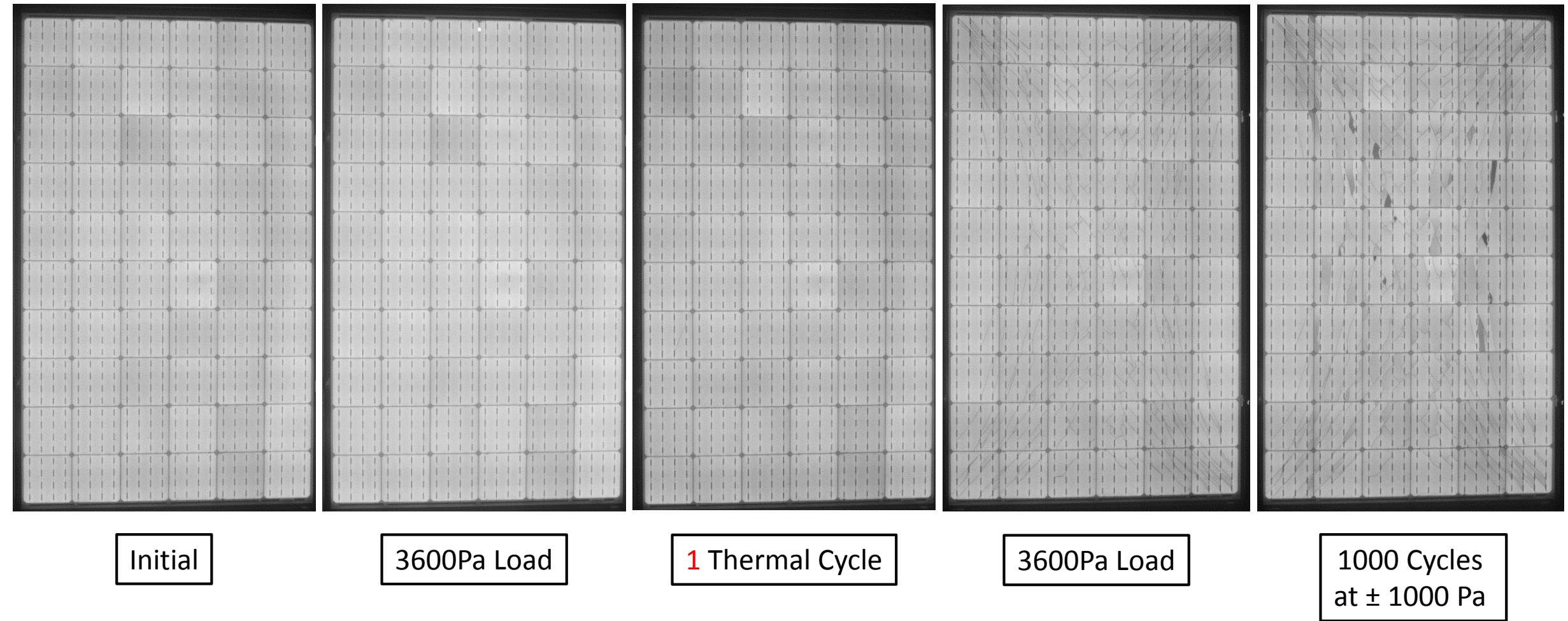


# EXTRA SLIDES

# Origin of Cell Cracks



# Impact of Single Thermal Cycle



# Cold Exposure on Wire Interconnect Module

